Vishay Semiconductors



HEXFRED<sup>®</sup> Ultrafast Diodes, 300 A (INT-A-PAK Power Modules)



INT-A-PAK

PRIMARY CHARACTERISTICS						
V <sub>R</sub>	1200 V					
V <sub>F</sub> (typical) at 300 A at 25 °C	2.18 V					
t <sub>rr</sub> (typical) at 45 A	233 ns					
I <sub>F(DC)</sub> at T <sub>C</sub>	300 A at 60 °C					
Package	INT-A-PAK					
Circuit configuration	Single diode					

#### FEATURES

- Electrically isolated: DCB base plate
- Standard JEDEC<sup>®</sup> package
- · Simplified mechanical designs, rapid assembly
- High surge capability
- Large creepage distances
- Case style INT-A-PAK
- Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

#### REMARKS

- Product reliability results valid for T<sub>J</sub> = 150 °C
- Recommended operation temperature T<sub>op</sub> = 150 °C

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Cathode to anode voltage	V <sub>R</sub>		1200	V		
Continuous forward current	1_	T <sub>C</sub> = 25 °C	375			
	IF	$T_{\rm C} = 60 \ ^{\circ}{\rm C}$	300	А		
Single pulse forward current	I <sub>FSM</sub>	T <sub>J</sub> = 25 °C	2400			
Maximum power dissipation	Р	T <sub>C</sub> = 25 °C	1040	w		
	PD	$T_{\rm C} = 60 \ ^{\circ}{\rm C}$	750			
RMS isolation voltage	V <sub>ISOL</sub>	50 Hz, circuit to base, all terminal shorted, t = 1 s	3500	V		
Junction temperature range	TJ		-40 to +150	°C		
Storage temperature range	T <sub>Stg</sub>		-40 to +150	U		

<b>ELECTRICAL SPECIFICATIONS PER LEG</b> ( $T_J = 25 \text{ °C}$ unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Cathode to anode breakdown voltage	V <sub>BR</sub>	I <sub>R</sub> = 500 μA	1200	-	-		
Maximum forward voltage	V <sub>FM</sub>	I <sub>F</sub> = 300 A	-	2.18	2.23	V	
		I <sub>F</sub> = 300 A, T <sub>J</sub> = 150 °C	-	2.24	2.47		
Maximum reverse leakage current	I <sub>RM</sub>	V <sub>R</sub> = 1200 V	-	0.06	0.2	mA	
		T <sub>J</sub> = 150 °C, V <sub>R</sub> = 1200 V	-	-	20	IIIA	





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<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 $^{\circ}$ C unless otherwise specified)							
PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNITS	
Diode reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C	I <sub>F</sub> = 45 A V <sub>R</sub> = 400 V dI <sub>F</sub> /dt = 500 A/μs	-	3.5	-	μC
		T <sub>J</sub> = 125 °C		-	10.4	-	
Reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	233	-	ns
		T <sub>J</sub> = 125 °C		-	396	-	
Reverse recovery current	I <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	30	-	A
		T <sub>J</sub> = 125 °C		-	53	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	SYMBOL TEST CONDITIONS		UNITS		
Maximum internal thermal resistance junction to case per leg	e, R <sub>thJC</sub>	DC operation	0.12	°C/W		
Typical thermal resistance, case to heatsink per module	R <sub>thCS</sub>	Mounting surface flat, smooth, and greased	0.05	C/W		
to heat Mounting torque ± 10 %	tsink	A mounting compound is recommended and the torque should be rechecked after a period of 3 hours	4 to 6	Nm		
busbar	sbar	to allow for the spread of the compound	- 10 0			
Approximate weight			200	g		
			7.1	OZ.		
Case style			INT-A	-PAK		

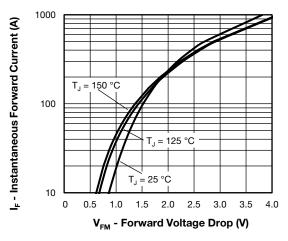


Fig. 1 - Typical Forward Voltage Drop Characteristics

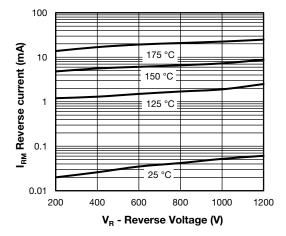


Fig. 2 - Typical Value of Reverse Current vs. Reverse Voltage



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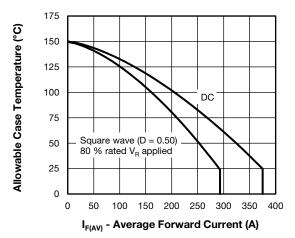


Fig. 3 - Maximum Allowable Case Temperature vs. Average Forward Current

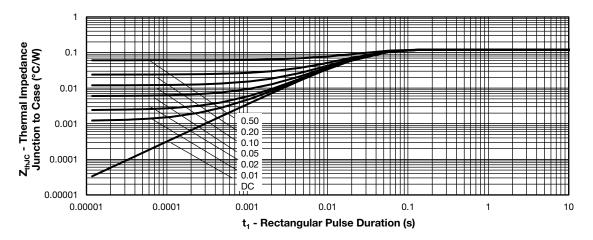


Fig. 4 - Maximum Thermal Impedance RthJC Characteristics

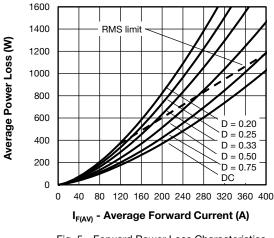


Fig. 5 - Forward Power Loss Characteristics

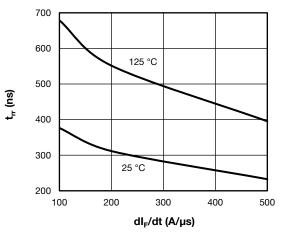


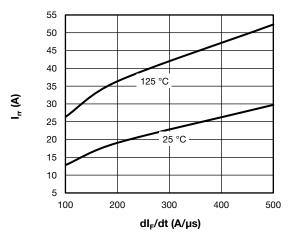
Fig. 6 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

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#### 12300 10300 125 °C 8300 Q<sub>rr</sub> (nC) 6300 4300 25 °C 2300 300 200 300 400 500 100 dl<sub>F</sub>/dt (A/µs)

Fig. 7 - Typical Reverse Recovery Charge vs. dl<sub>F</sub>/dt

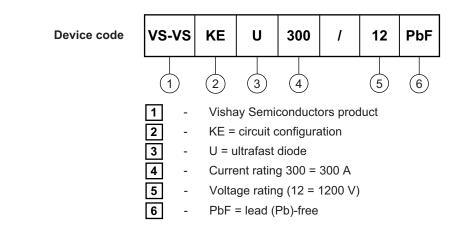


VS-VSKEU300/12PbF

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Fig. 8 - Typical Reverse Recovery Current vs. dl<sub>F</sub>/dt

#### **ORDERING INFORMATION TABLE**



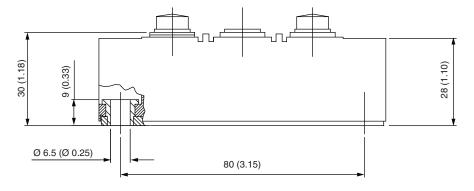
#### **CIRCUIT CONFIGURATION**

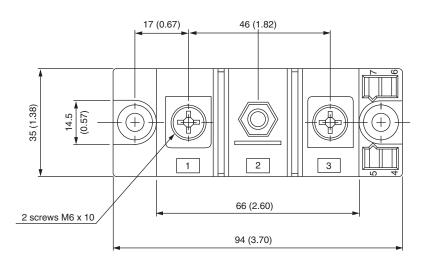


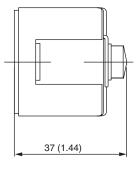


### Vishay Semiconductors

### DIMENSIONS in (inches) millimeters INT-A-PAK DBC







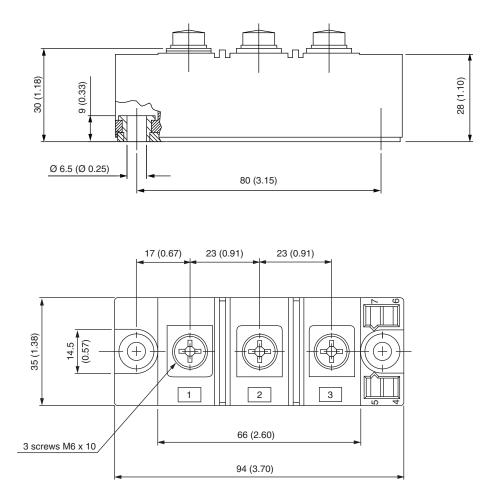


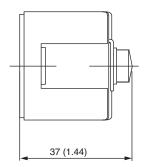
# **Outline Dimensions**

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## **INT-A-PAK DBC**

#### **DIMENSIONS** in millimeters (inches)







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Revision: 01-Jan-2025

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